

REMARKS

Claims 1 through 17 are pending in the application with claims 4, 12, 13, 14, 15, 16, and 17 having been withdrawn from further examination. Of the claims currently under consideration, claims 1 and 9 are independent, and claims 1, 6, 7, and 9 have been amended. No new matter has been added. Reconsideration and further examination are respectfully requested.

Claim Rejections

Claims 1, 2, 3, and 5 through 11 are rejected under 35 U.S.C. § 102(b) as being anticipated by Japanese document JP 11-219825 ["JP'825"]. Reconsideration and withdrawal of the rejection are respectfully requested.

Claims 1 and 9

Amended independent claim 1 describes a device including a first portion of an inductor and a second portion of the inductor. The first portion is disposed in a first layer of a multilayer substrate and the second portion is disposed in a second layer of the multilayer substrate. The second portion is coupled at a plurality of locations to the first portion and a shielding plane is disposed between the first portion and the second portion.

The art of record is not seen to disclose or suggest the above features of independent claim 1. In particular, the art of record is not seen to disclose or suggest a first portion of an inductor disposed in a first layer of a multilayer substrate and coupled at a plurality of locations to a second portion of the inductor disposed in a second layer of the multilayer substrate.

JP'825 illustrates a surface mounted transformer that includes dielectric sheets 7a and 7b and spiral inductors L1 and L2. Spiral inductor L1 is located on an upper surface of dielectric sheet 7a and spiral inductor L2 is located on an upper surface of dielectric sheet 7b. The inner most end of inductor L1 is connected to connection sheet 2 and an outer most end of inductor L1 is connected to the outer most end of inductor L2. Inductors L1 and L2 are not connected at any other points.

Accordingly, JP'825 cannot be seen to disclose or to suggest a first portion of an inductor disposed in a first layer of a multilayer substrate and coupled at a plurality of locations to a second portion of the inductor disposed in a second layer of the multilayer substrate.

In view of the foregoing, amended independent claim 1 is believed to be in condition for allowance. Claims 2, 3, 5, 6, 7, and 8 depend from claim 1 and are therefore also believed to be allowable for at least the foregoing reasons.

Amended independent claim 9 relates to a method in which a first portion of an inductor is fabricated in a first layer of a multilayer substance, a second portion of the inductor is fabricated in a second layer of the multilayer substrate, and the first portion is coupled to the second portion at a plurality of locations. In view of the foregoing, amended independent claim 9 and its respective dependent claims are also believed to be in condition for allowance.

CONCLUSION

The outstanding Office Action presents a number of characterizations regarding the applied references, some of which are not directly addressed by this response. Applicants do not necessarily agree with the characterizations and reserve the right to further discuss those characterizations.

For at least the reasons given above, it is submitted that the entire application is in condition for allowance and such action is respectfully requested at the Examiner's earliest convenience. Alternatively, if there remains any question regarding the present application or any of the cited references, or if the Examiner has any further suggestions for expediting allowance of the present application, the Examiner is kindly invited to contact the undersigned via telephone at (203) 972-4981.

Respectfully submitted,



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